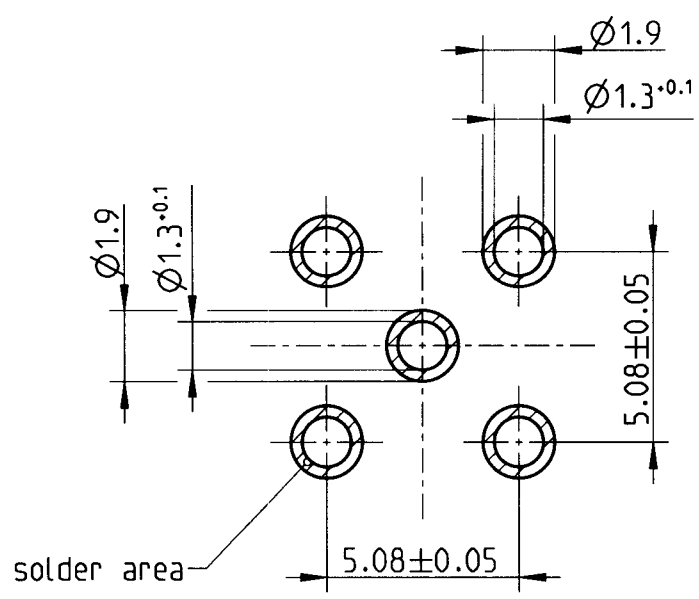


All rights reserved. Reproduction of this document is prohibited without written authority from the proprietor. Property of Rosenberger Hochfrequenztechnik.

Leiterplatten-Layout  
 PCB layout  
 B 30



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

fuer diese technische Unterlage behalten wir uns alle Rechte vor (DIN 34)

Formzahl: TCC 06 05 02 A - Einzelteil  
 Date: 14. JUN 2006 10:00:00  
 Version: 1.1

-METRIC-

ISO-Projektion  
 Methode E

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance <b>ISO 2768 RN 006-01</b> m-H dimensions <0,5 and symmetry		scale: 5:1 weight(g): surface(mm <sup>2</sup> ):	
		material:			
		date drawn 15.02.2001 A_Nobis check 20.3.06 appr.		<b>Leiterplatten-Layout          PCB layout</b>	
		name title:			
g00	06-0194	S_Krautenbac	24.03.2006	drawing-no.: MB_30 sheet: 1 of: 1	
f00	04-0709	A_Nobis	22.11.2004		
e00	02-0124	A_Nobis	01.10.2003		
d00	01-0425	A_Nobis	06.09.2001		
c00	01-0266	V_Spitzauer	13.06.2001	distribution to: FE AZ QSM RMT . X . . . .	
rev. change-no name date		date		remarks: .	